

ABSTRACT

This curable resin film is attached to a surface having bumps of a semiconductor wafer and is cured so as to form a first protective film on the surface, and when the

5 curable resin film is cured by being heated at 160°C for one hour, a yellow index (YI₁) after curing is equal to or lower than 45, or when the curable resin film is cured by being irradiated with ultraviolet rays under conditions of illuminance of 230 mW/cm², and light intensity of 510 mJ/cm², a yellow index (YI₂) after curing is equal to or lower than 45.

The first protective film forming sheet is provided with a first supporting sheet, and the

10 curable resin film is provided on one surface of the first supporting sheet.